

Material Declaration Data Sheet

Model: **Product Server P4000CP4, Boards S2600CP2, CP4**

Manufacturer: Intel Corporation

Note: This declaration applies to all associated product codes starting on Page 2

Lead Free (Pb) Product: **Yes/RoHS6, 6/6**

Date: November 29, 2012

Restriction on Hazardous Substances (RoHS) Compliance

RoHS Definition

- Quantity limit of 0.1% by mass (1000PPM) for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE)
- Quantity limit of 0.01% by mass (100 PPM) for: Cadmium

Intel understands RoHS requires: Lead and other materials banned in the RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU or (2) an approved/pending exemption applies. (Note: RoHS implementing details are not fully defined and may change.)

RoHS Declaration

- 6a** Lead as an alloying element in steel containing up to 0.35 % lead by weight.
- 6b** Lead as an alloying element in aluminum containing up to 0.4 % lead by weight.
- 6c** Lead as an alloying element in copper containing up to 4 % lead by weight.
- 7a** Lead in high melting temperature type solders (i.e. lead based alloys containing 85 % by weight or more lead)
- 7b** Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
- 7c-I** Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound.
- 7c-II** Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher.
- 7c-III** Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC.
- 8b** Cadmium and its compounds in electrical contacts.
- 11b** Lead used in other than C-press compliant pin connector systems.
- 13b** Cadmium and lead in filter glasses and glasses used for reflectance standards.
- 15** Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.
- 20** Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCDs)
- 21** Lead and cadmium in printing inks for the application of enamels on glasses, such as borosilicate and soda lime glasses.
- 24** Lead in solders for the soldering to machined through hole discoidal and planar array ceramic capacitors
- 25** Lead oxide in surface conduction electron emitter displays (SED) used in structural elements: notably in the seal frit and frit ring.
- 31** Lead in soldering materials in mercury free flat fluorescent lamps (which e.g. are used for liquid crystal displays, design or industrial lighting).
- 33** Lead in solders for the soldering of thin copper wires of 100um diameter and less in power transformers.
- 34** Lead in cermet-based trimmer potentiometer elements.
- Other (Include exemption number)

Where the product is declared to meet RoHS requirements, it has been verified to be in conformance with 2011/65/EU as we currently understand the requirements. Intel has systems in place to verify conformance with all applicable environmental requirements and to the best of our knowledge the information is true and correct.

INTEL ACCEPTS NO DUTY TO UPDATE THIS DECLARATION OR TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION. INTEL SHALL NOT BE LIABLE FOR ANY DAMAGES, DIRECT OR INDIRECT, CONSEQUENTIAL OR OTHERWISE, SUFFERED BY USERS OR THIRD PARTIES AS A RESULT OF THE USERS RELIANCE ON INFORMATION IN THIS DECLARATION THAT HAS BEEN UPDATED OR CHANGED.

Product Code Information



Product Code	Description	*RoHS Exemption #
P4308CP4MHEN	S2600CP4 board P4000 pedestal chassis, rackable* 8x3.5" HSB, 1 550W PSU, Silver efficiency, RAID C600 Upgrade Key RKSATA8	6a,6b,6c,7a,7c1,15
P4308CP4MHGC	S2600CP4 board P4000 Pedestal chassis, rackable* 8x3.5" HSB, 2 750W CRPS, Platinum efficiency, RAID C600 Upgrade Key RKSATA8	6a,6b,6c,7a,7c1,15
P4208CP4MHGC	S2600CP4 board P4000 Pedestal chassis, rackable* 8x2.5" HSB, 2 750W CRPS, Platinum efficiency, RAID C600 Upgrade Key RKSAS8	6a,6b,6c,7a,7c1,15
P4308XXMHEN	P4000 Pedestal chassis KDK	6a,6b,6c,7a,7c1
DBS2600CP2IOG	Intel® Server Bd S2600CP2 Retail Single pk, Dual NIC, 6-Gb/s SAS	7a, 7c1, 15
DBS2600CP2	Intel® Server Board S2600CP2 Retail Single pk; Dual NIC, C600	7a, 7c1, 15
BBS2600CP2J	Intel® Server Board S2600CP2 10-pack; Dual NIC, C602J	7a, 7c1, 15
BBS2600CP2	Intel® Server Board S2600CP2 OEM 10-pack with Dual NIC	7a, 7c1, 15
BBS2600CP4	Intel® Server Board S2600CP4 OEM 10-pack with Quad NIC	7a, 7c1, 15
DBS2600CP4	Intel® Server Board S2600CP4 Retail Single pk w/Quad NIC	7a, 7c1, 15
DBS2600CP4IOG	Intel® Server Board S2600CP4 Rtl Single pk, Quad NIC, 6Gb/s SAS	7a, 7c1, 15

FUPNRPSADP	P4000 Non-Redundant Power Supply adaptor kit	Compliant without exemption
FUPCRPSCAGE	Common Pedestal CRPS PSU cage assembly	Compliant without exemption
FUPPDBLC	Power Distribution Board Spare (Low Current) for P4000 chassis	Compliant without exemption
FUPPDBHC	Power Distribution Board Spare (High Current), P4000 chassis	7a, 7c1
AUPSRCBTP	Spare/Accessory SRC-B tower passive heat sinks	Compliant without exemption
BXSTS200P	Intel Boxed Thermal Solutions, passive 25.5mm heat sink	Compliant without exemption
BXSTS200C	Intel Boxed Thermal Solutions, heat sink combo with removable fan supports E5-2600 processors	6c, 7a, 7c1
FUPMLHSFAN	80mm system fan kit for P4000M/P4000L server	7a, 7c1
FUPNHFANCPU	120mm fixed fan	6c, 7a, 7c1
FUPMNHFANPCI	Fixed Fan spare kit for P4000M (24") for PCI area fan	6c,7a,7c1,7c2
FCPUPMAD	Air duct and unique cable kit for Intel® Server Board S2600CP to be used Intel® Server Chassis P4000M	Compliant without exemption
AXXELVRAIL	Value Rail Kit	Compliant without exemption
AXX3U5UPRAIL	Advanced rail kit for P4000 Server Chassis used when converting Pedestal chassis to 4U rack chassis	Compliant without exemption
AXX3U5UCMA	Rack Cable Management for use with Advanced Rail Kit AXX3U5UPRAIL	Compliant without exemption
FUPBEZELFIX	Bezel spare for P4000 server chassis with fixed drives (no door)	Compliant without exemption
FUPBEZELHSD	Bezel spare for P4000 server chassis with Hot Swap HDDs (w/door for HS bays)	Compliant without exemption
AUPBEZEL4UF	Rack bezel kit for converting P4000 pedestal server chassis to rack chassis	Compliant without exemption
AUPBEZEL4UD	Rack bezel accessory for P4000 chassis in rack configuration	Compliant without exemption

	- security door only	
FXXFPANEL	Front Panel board spare for P4000 server chassis	7c1, 7c2
A4ULCP	LCP Module (local control panel)	7c1
AXX2IOS	I/O Shield spare/accessory for Intel® Server Board S2600CP2	Compliant without exemption
AXX4IOS	I/O Shield spare/accessory for Intel® Server Board S2600CP4	Compliant without exemption
AUPMGPUBR	Bracket for securing full length GPU cards to fan bulkhead, for use in P4000M	Compliant without exemption
FUPMMSK	Chassis Maintenance kit for UPM – (Mechanical Spares Kit)	Compliant without exemption
FUPMESK	Chassis Maintenance kit for UPM – (Electric Spares Kit)	Compliant without exemption
FPWRCABLENA	North American Power Cord Spare	Compliant without exemption
FUP8X35HSBP	Spare 8x3.5" Hot Swap Backplane	7c1
FXX8X25HSBP	8x2.5" hot swap HSBP spare (for R2200, and P4200 Chassis families)	7c1
FXX8X25DPBP	Spare 8x2.5" Dual Port Hot Swap Backplane	7c1
FUP4X35HSDK	3.5" Hot Swap Drive Kit for P4000 server chassis	7c1
FUP8X35HSDK	8x3.5" Hot Swap Drive Cage Kit for P4000 server chassis	7c1
FUP8X25HSDKS	8x2.5 Hot Swap Drive Cage Kit for P4000 server chassis	7c1
FXX35HSADPB	3.5" HDD Hot Swap Drive Carrier spares for P4300 chassis	Compliant without exemption
FXX25HSCAR	2.5" HDD Hot Swap Drive Carrier spares for P4200	Compliant without exemption
FUP4X35NHDK	Fixed Drive Carrier spare for P4300 server chassis (compatible with 2.5" HDDs/SSDs)	Compliant without exemption
RMS25PB080	Intel® Integrated RAID Module RMS25PB080, PCIe Slot, LSI2208 ROC, 8P Internal SAS/SATA	7a, 7c1, 15
RMS25PB040	Intel® Integrated RAID Module RMS25PB040, PCIe Slot, LSI2208 ROC, 4P Internal SAS/SATA	7a, 7c1, 15
RMT3PB080	Intel® Integrated RAID Module RMT3PB080, PCIe Slot, LSI2208 ROC, 8P Internal SATA (only)	7a, 7c1, 15
RMS25KB040	Intel® Integrated RAID Module RMS25KB040, PCIe Slot, LSI2308 SAS Chip, 4P Internal SAS, LSI IR RAID 0,1,1E	7a, 7c1, 15
RMS25CB080	Intel® Integrated RAID Module RMS25CB080, SIOM Connector, LSI2208 ROC, 8P Internal SAS, MegaRAID SW Stack, 1GB DDR3, R0,1,10,5,50,6,60	7a, 7c1, 15
RMS25CB040	Intel® Integrated RAID Module RMS25CB040, SIOM Connector, LSI2208 ROC, 4P Internal SAS, MegaRAID SW Stack, 1GB DDR3, R0,1,10,5,50,6,60	7a, 7c1, 15
RMT3CB080	Intel® Integrated RAID Module RMT3CB080, SIOM Connector, LSI2208 ROC, 8P Internal SATA (only), MegaRAID SW Stack, 512MB DDR3, R0,1,10,5,50,6,60	7a, 7c1, 15
RMS25JB080	Intel® Integrated RAID Module RMS25JB080, SIOM Module Slot, LSI2308 SAS Chip, 8P Internal SAS, LSI IR RAID 0,1,1E	7a, 7c1, 15
RMS25JB040	Intel® Integrated RAID Module RMS25JB040, SIOM Module Slot, LSI2308 SAS Chip, 4P Internal SAS, LSI IR RAID 0,1,1E	7a, 7c1, 15
AXX1FDRIBIOM	Single port, FDR speed Infiniband module with QSFP	7a, 7c1, 15
AXXTPME5	Trusted Platform Module for server systems	7c1
AXX2UPCIEX16	2U PCIe x16 riser, 1 slot, x16 electrical/x16 mechanical	Compliant without exemption
AXX2UPCIEX8X4	2U PCIe x16 riser, 3 slots, one x8 electrical/x16 mechanical + two x4 electrical/x8 mechanical	Compliant without exemption
AXX1UPCIEX16	1U PCIe x16 riser, 1slot, x16 electrical/x16 mechanical	Compliant without exemption
RES2CV240	Integrated 24-port 6G SAS expander	7a, 7c1, 15


RES2CV360	Integrated 36-port 6G SAS expander	7a, 7c1, 15
AXX4P1GBPWL1OM	Quad port 1GbE IO Module ,Intel® Ethernet Controller I350	7a, 7c1, 15
AXX10GBTWL1OM	Dual RJ-45 port 10GBASE-T IO module, Intel I350 Ethernet	7a, 7c1, 15
AXX10GBNIA1OM	Dual SFP+ port 10GbE IO module,Intel® 82599 10 Gigabit	7a, 7c1, 15
AXXRSBBU9	Intel® RAID Smart Battery AXXRSBBU9 for mainstream RS25, RMS25, RT3 and RMT3 family RAID products.	6a, 7c1
AXXRMFBU2	Maintenance Free Backup Unit,NAND Flash & Supercapacitor	6a, 7c1
RKSATA4R5	Intel® RAID C600 Upgrade Key RKSATA4R5, Black	7c1
RKSATA8	Activation key for 8 SATA ports and includes RSTe SW RAID 0/1/10/5 and LSI SW RAID 0/1/10 , Blue	7c1
RKSATA8R5	Activation key for 8 SATA ports and includes RSTe SW RAID 0/1/10/5 and LSI SW RAID 0/1/10/5 (LSI SWR5), White	7c1
RKSAS4	Intel® RAID C600 Upgrade Key RKSAS4, Green	7c1
RKSAS4R5	Intel® RAID C600 Upgrade Key RKSAS4R5, Yellow	7c1

RKSAS8	Activation key for 8 SAS ports and includes RSTe SW RAID 0/1/10 (no RAID 5) and LSI SW RAID 0/1/10 , Orange	7c1
RKSAS8R5	Activation key for 8 SAS ports and includes RSTe SW RAID 0/1/10 (no RAID5) & SW RAID 0/1/10/5 (LSI SWR5), Purple	7c1
AXXRMM4	Remote Management Module, KVM ,Dedicated NIC module	7c1
AXXRMM4LITE	Remote Management Module for upgrading to Remote KVM	7c1
AXXRMM41OM	PCI Express x16 (164 pin) rIOM riser & rIOM carrier board kit	7c1
FXX460GCRPS	460W Common Redundant PS, 80 Plus Gold Efficiency	6a,6b,6c,7a,7c1
FUP550SNRPS	550W Fixed Power Supply, 80 Plus Silver Efficiency	6a,6b,6c,7a,7c1
FXX750PCRPS	750W Common Redundant PS, 80 Plus Platinum Efficiency	6a,6b,6c,7a,7c1
FXX1200PCRPS	1200W Power Supply Spare, 80 Plus Platinum Efficiency	6a,6b,6c,7a,7c1
FHW1U16RISER	Riser Spare	7a
AXXCBL650MSMS	Kit of 2 cables, 650mm length, straight SFF-8087 to SFF-8087 connectors.	Compliant without exemptions
AXXCBL850MS7R	Kit of 2 cables, 850mm length, straight SFF-8087 to right angle 7-pin SATA connectors.	Compliant without exemptions

* RoHS Exemption # corresponds with exemption #'s found on page 1.

关于符合中国《电子信息产品污染控制管理办法》的声明
 Management Methods on Control of Pollution from
 Electronic Information Products
 (China RoHS declaration)


产品中有毒有害物质的名称及含量

部件名称 (Parts)	有毒有害物质或元素					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr6+)	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
印刷板组件 Printed Board Assemblies (PBA)	×	○	○	○	○	○
<p>○：表示该有毒有害物质在该部件所有均质材料中的含量均在 SJ/T 11363-2006 标准规定的限量要求以下。</p> <p>○：Indicates that this hazardous substance contained in all homogeneous materials of this part is below the limit requirement in SJ/T 11363-2006.</p> <p>×：表示该有毒有害物质至少在该部件的某一均质材料中的含量超出 SJ/T 11363-2006 标准规定的限量要求。</p> <p>×：Indicates that this hazardous substance contained in at least one of the homogeneous materials of this part is above the limit requirement in SJ/T 11363-2006.</p> <p>对销售之日的所售产品, 本表显示我公司供应链的电子产品信息产品可能包含这些物质。注意：在所售产品中可能会也可能不会含有所有所列的部件</p> <p>This table shows where these substances may be found in the supply chain of our electronic information products, as of the date of sale of the enclosed product. Note that some of the component types listed above may or may not be a part of the enclosed product.</p> <p>除非另外特别的标注, 此标志为针对所涉及产品的环保使用期限标志。某些可更换的零部件可能会有一个不同的环保使用期限(例如, 电池单元模块)。</p> <p>此环保使用期限只适用于产品在产品手册中所规定的条件下工作。</p>						
						
<p>The Environment-Friendly Use Period (EFUP) for all enclosed products and their parts are per the symbol shown here, unless otherwise marked. Certain field-replaceable parts may have a different EFUP (for example, battery modules) number. The Environment-Friendly Use Period is valid only when the product is operated under the conditions defined in the product manual.</p>						

关于符合中国《电子信息产品污染控制管理办法》的声明

Management Methods on Control of Pollution from
Electronic Information Products
(China RoHS declaration)

产品中有毒有害物质的名称及含量

部件名称 (Parts)	有毒有害物质或元素					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr6+)	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
主板组件 Motherboard Assembly	×	○	○	○	○	○
<p>○：表示该有毒有害物质在该部件所有均质材料中的含量均在 SJ/T 11363-2006 标准规定的限量要求以下。</p> <p>○：Indicates that this hazardous substance contained in all homogeneous materials of this part is below the limit requirement in SJ/T 11363-2006.</p> <p>×：表示该有毒有害物质至少在该部件的某一均质材料中的含量超出 SJ/T 11363-2006 标准规定的限量要求。</p> <p>×：Indicates that this hazardous substance contained in at least one of the homogeneous materials of this part is above the limit requirement in SJ/T 11363-2006.</p> <p>对销售之日的所售产品,本表显示我公司供应链的电子产品信息产品可能包含这些物质。注意:在所售产品中可能会也可能不会含有所有所列的部件。</p> <p>This table shows where these substances may be found in the supply chain of our electronic information products, as of the date of sale of the enclosed product. Note that some of the component types listed above may or may not be a part of the enclosed product.</p>						
<p>除非另外特别的标注,此标志为针对所涉及产品的环保使用期限标志。某些可更换的零部件可能会有一个不同的环保使用期限(例如,电池单元模块)。</p> <p>此环保使用期限只适用于产品在产品手册中所规定的条件下工作。</p>						
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 Management Methods on Control of Pollution from
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 (China RoHS declaration)

产品中有毒有害物质的名称及含量

部件名称 (Parts)	有毒有害物质或元素 (Hazardous Substance)					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr6+)	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
机箱子组件 Chassis subassembly	×	○	○	○	○	○
电源 Power Supply	×	○	○	○	○	○
印刷板组件 Printed Board Assemblies (PBA)	×	○	○	○	○	○

○：表示该有毒有害物质在该部件所有均质材料中的含量均在 SJ/T 11363-2006 标准规定的限量要求以下。

○：Indicates that this hazardous substance contained in all homogeneous materials of this part is below the limit requirement in SJ/T 11363-2006.

×：表示该有毒有害物质至少在该部件的某一均质材料中的含量超出 SJ/T 11363-2006 标准规定的限量要求。

×：Indicates that this hazardous substance contained in at least one of the homogeneous materials of this part is above the limit requirement in SJ/T 11363-2006.

对销售之日的所售产品, 本表显示我公司供应链的电子产品信息产品可能包含这些物质。注意: 在所售产品中可能会也可能不会含有所有所列的部件
 This table shows where these substances may be found in the supply chain of our electronic information products, as of the date of sale of the enclosed product. Note that some of the component types listed above may or may not be a part of the enclosed product.

除非另外特别的标注, 此标志为针对所涉及产品的环保使用期限标志. 某些可更换的零部件可能会有一个不同的环保使用期限 (例如, 电池单元模块).

此环保使用期限只适用于产品在产品手册中所规定的条件下工作.



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